





(1,00 mm) .0394"

MB1 SERIES

MINI EDGE CARD SOCKET WITH GUIDES

(0,80 mm) .031" PCB, (1,60 mm) .062" PCB

Mates with:

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material: Black LCP Contact Material: BeCu Plating: Sn or Au over 50μ" (1,27 μm) Ni Current Rating: 2.2 A per pin (6 pins powered) Operating Temp Range: -55°C to +125°C Insertion Depth: (5,26 mm) .207" to (6,10 mm) .240" RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes SMT Lead Coplanarity: (0,10 mm) .004" max (20-30) (0,15 mm) .006" max (40-50)

RECOGNITIONS

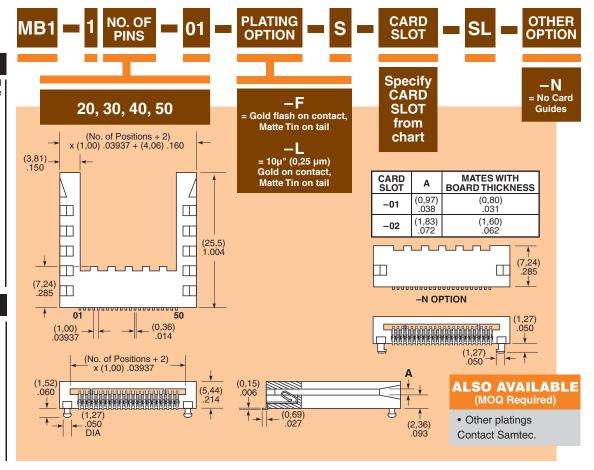
For complete scope of recognitions see www.samtec.com/quality



Note: Patented

Important Note: Samtec recommends that pads on the mating board be Gold plated.

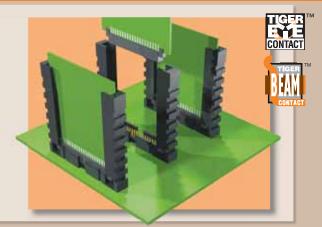
Note: Some sizes, styles and options are non-standard, non-returnable.



OTHER SOLUTIONS

Flex Card System

- .050" (1,27 mm) (FCF/EMF Series) systems
- · Vertical and horizontal
- · Header with snap-on card guides for design flexibility
- · Elevated design now available
- PCMCIA (PCMT/PCMS Series) Compact Flash (CFT/CFS Series) compatible applications available
- · Ideal for multiple add-on cards
- · Solder locks for mechanical stability
- Any size from 40 to 100 contacts



Due to technical progress, all designs, specifications and components are subject to change without notice.

AI.